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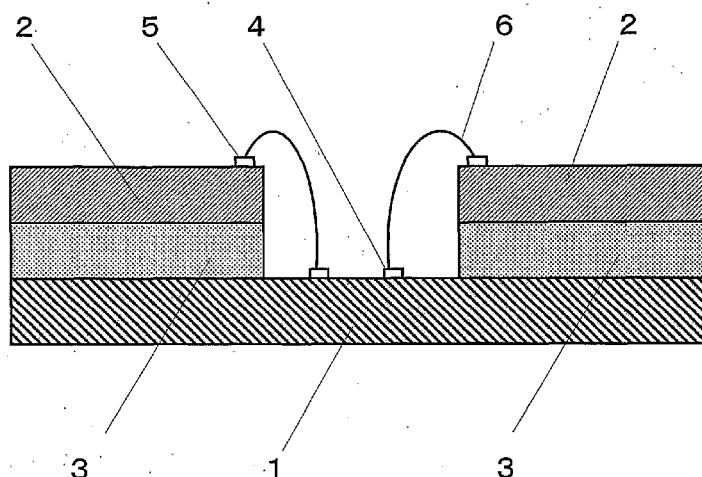
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(54) Title: INSULATING LIQUID DIE-BONDING AGENT AND SEMICONDUCTOR DEVICE



(57) Abstract: An insulating liquid die-bonding agent for bonding a semiconductor-chip-mounting member to an active surface of a semiconductor chip, said agent comprising: (A) a mixture of (a-1) an organopolysiloxane resin having alkenyl groups and (a-2) a linear-chain organopolysiloxane having in one molecule at least two alkenyl groups; (B) an organopolysiloxane having in one molecule at least two silicon-bonded hydrogen atoms; (C) an organic silicon compound having in one molecule at least one silicon-bonded alkoxy groups; (D) insulating spherical silicone rubber particles having an average diameter of 0.1 to 50 μm and having a type A durometer hardness according to JIS K 6253 equal to or below 80; and (E) a hydrosilylation-reaction catalyst, may not damage the active surface of the semiconductor chip, is well suited for screen printing, is resistant to the formation of voids on the interface between the semiconductor chip and the die-bonding agent, and does not lose its wire-bonding properties.

WO 2007/026727 A1